

Electrostatic Discharged Protection Devices (ESD) Data Sheet

Description

The SBD03C05L01 is designed to replace multilayer varistors (MLVs) in portable applications such as cell phones, notebook computer, and PDAs. It offer superior electrical characteristics such as lower clamping voltage and no device degradation when compared to MLVs. It is designed to protect sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD), lightning, electrical fast transients (EFT), and cable discharge events (CDE).

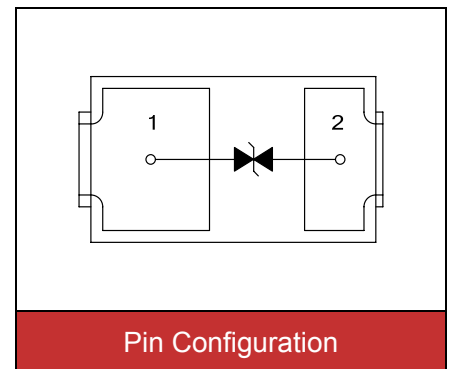


Contact : ±8kV
Air : ±15kV



Features

- IEC61000-4-2 ESD 15KV Air, 8KV contact compliance
- DFN1608 surface mount package
- Protects bi-directional line
- Working voltage: 5V
- Low leakage current
- Low operating and clamping voltages
- Solid-state silicon avalanche technology
- Lead Free/RoHS compliant
- Solder reflow temperature: Pure Tin-Sn, 260~270°C
- Flammability rating UL 94V-0
- Meets MSL level 1, per J-STD-020
- Marking: 5B



Applications

- | | |
|---|---|
| <ul style="list-style-type: none"> ● Cellular handsets & Accessories ● Cordless phones ● Personal digital assistants (PDAs) ● Notebooks & Handhelds | <ul style="list-style-type: none"> ● Portable instrumentation ● Digital cameras ● Peripherals ● MP3 players |
|---|---|

Maximum Ratings

Rating	Symbol	Value	Unit
ESD voltage (Contact discharge)	V_{ESD}	±8	kV
ESD voltage (Air discharge)		±15	
Storage & operating temperature range	T_{STG}, T_J	-55~+150	°C

Electrical Characteristics ($T_J=25^{\circ}\text{C}$)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Reverse stand-off voltage	V_{RWM}				5.5	V
Reverse breakdown voltage	V_{BR}	$I_{BR}=1\text{mA}$	6		8	V
Reverse leakage current	I_R	$V_R=5.5\text{V}$			5	μA
Clamping voltage ($t_p=8/20\mu\text{s}$)	V_C	$I_{PP}=1\text{A}$			8	V
Clamping voltage ($t_p=8/20\mu\text{s}$)	V_C	$I_{PP}=5\text{A}$			12	V
Off state junction capacitance	C_J	0Vdc, f=1MHz		30		pF

Typical Characteristics Curves

Figure 1. Power Derating Curve

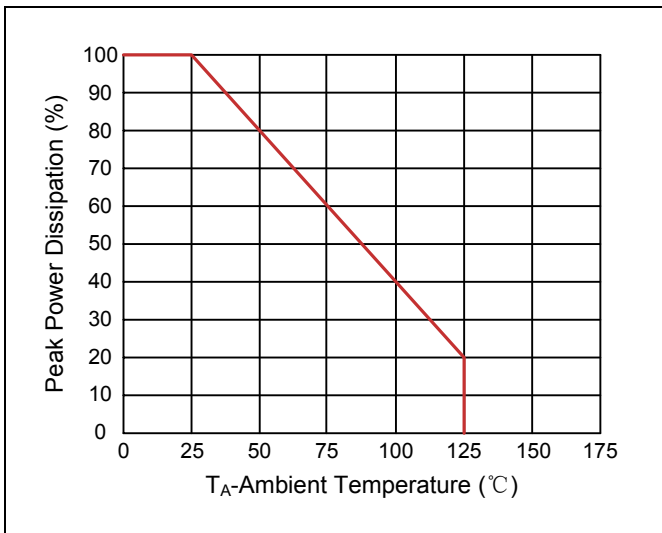


Figure 2. Pulse Waveforms

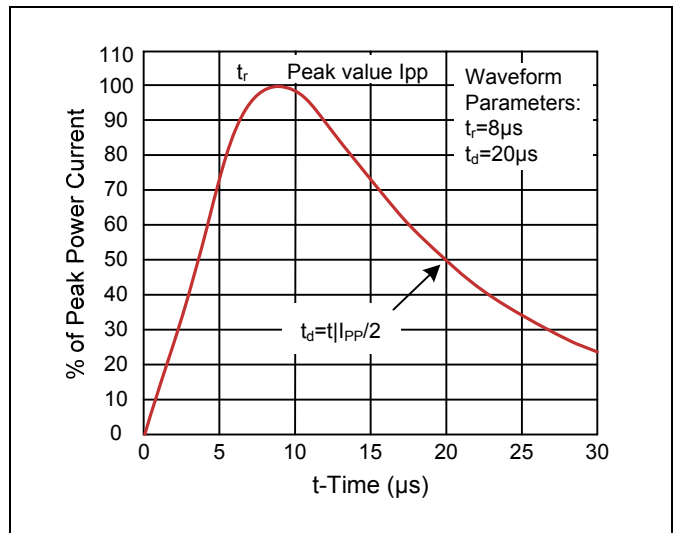


Figure 3. Clamping Voltage vs. Peak Pulse Current

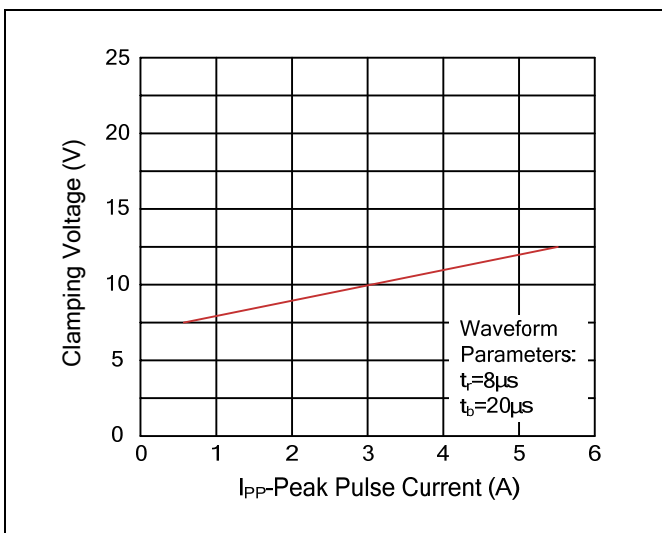
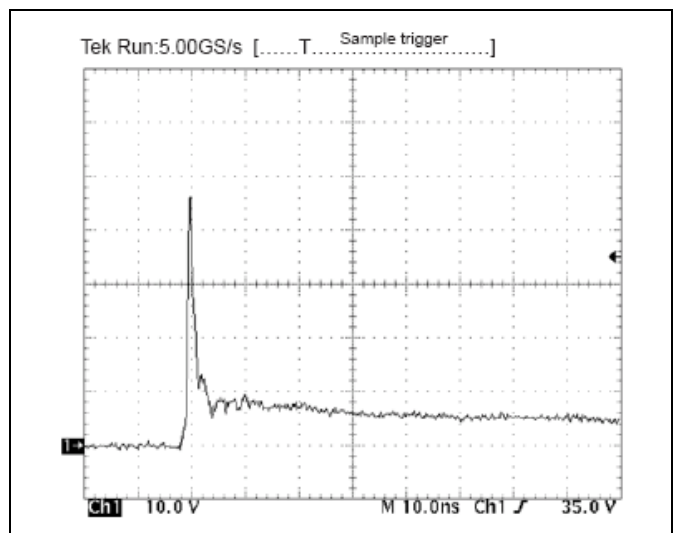
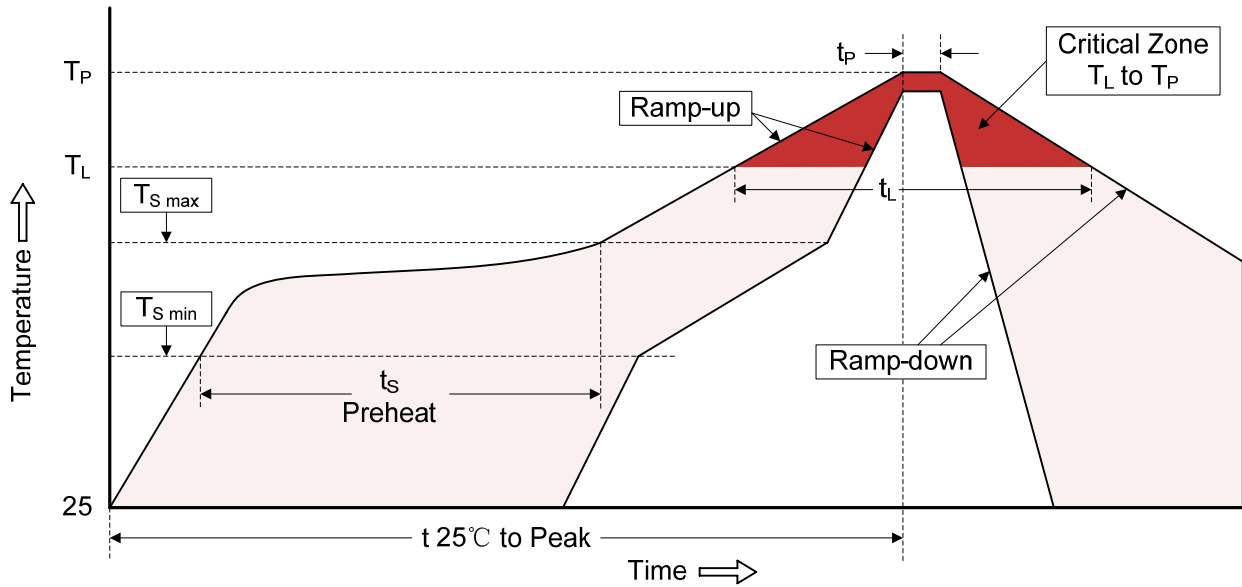


Figure 4. ESD Clamping(8kV Contact IEC61000-4-2)



Recommended Soldering Conditions

Reflow Soldering



Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	3°C/second max.
Preheat -Temperature Min ($T_{S\ min}$) -Temperature Max ($T_{S\ max}$) -Time (min to max) (t_s)	150°C 200°C 60-180 seconds
$T_{S\ max}$ to T_L -Ramp-up Rate	3°C/second max.
Time maintained above: -Temperature (T_L) -Time (t_L)	217°C 60-150 seconds
Peak Temperature (T_P)	260°C
Time within 5°C of actual Peak Temperature (t_P)	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

Dimensions (DFN1608)

Symbol	Dimension (mm)			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	0.45	0.65	0.018	0.026
A1	0.04Typ.		0.002	
D	1.55	1.65	0.061	0.065
E	0.67	0.75	0.026	0.030
F	0.75	0.85	0.030	0.033
L1	0.72	0.80	0.028	0.031
L2	0.32	0.50	0.013	0.020

Packaging

Tape		Symbol	Dimension (mm)
		W	8.00±0.30
		P0	4.00±0.10
		P1	4.00±0.10
		P2	2.00±0.10
		D0	Φ1.50±0.10
		D1	Φ0.50±0.05
		E	1.75±0.10
		F	3.50±0.10
		A	0.93±0.05
		B	1.74±0.05
		K	0.70±0.05
		t	0.20±0.05
		Reel	
		D2	Φ13.0
		W1	9.5
		Quantity: 5000PCS	